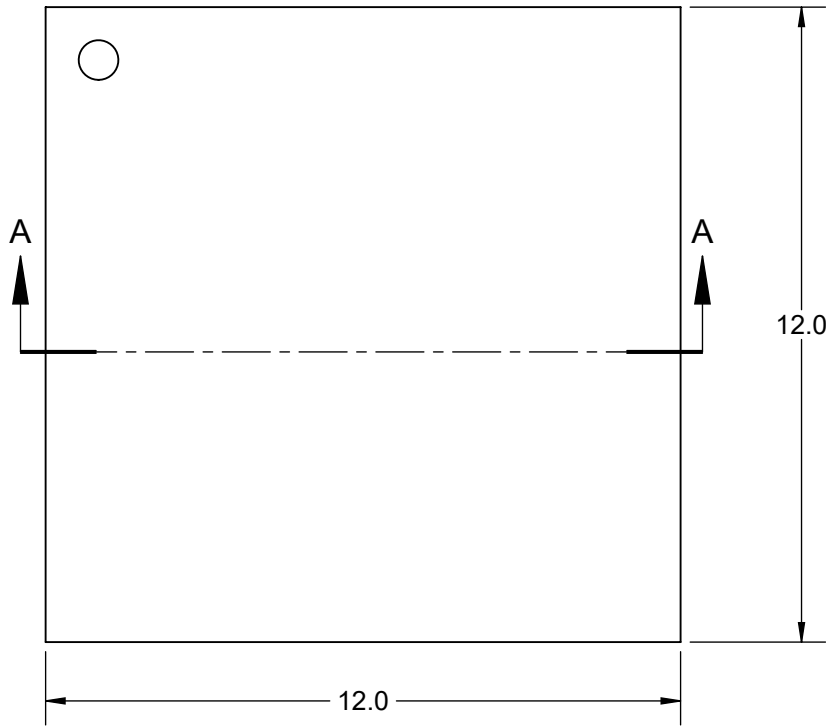
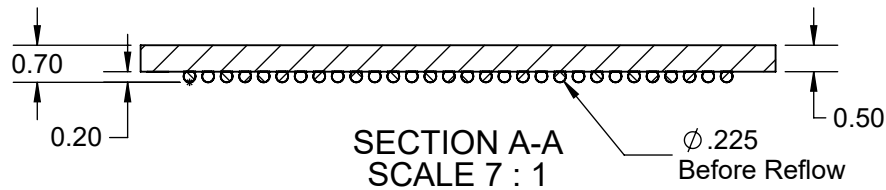
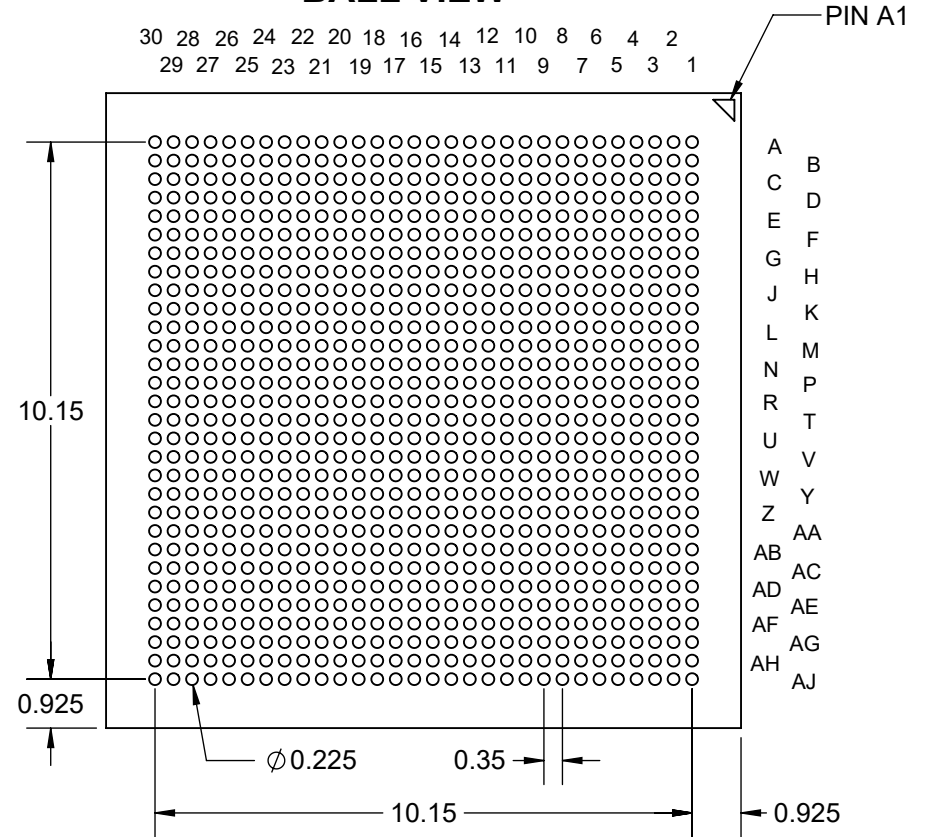


TOP VIEW



BALL VIEW



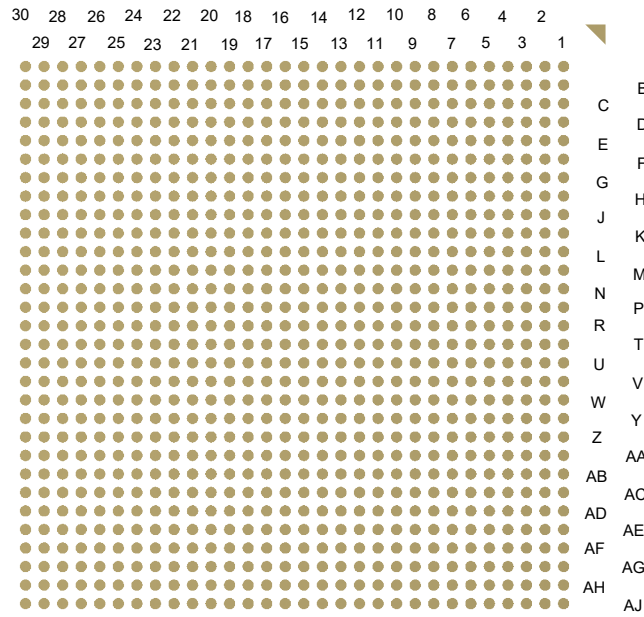
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS: MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.225mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.20mm (8 MIL).
- 5) PAD Cu DIAMETER: 0.25mm (10 MIL).
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE IS OPTIONAL.
- 8) ISOLATED PAD PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

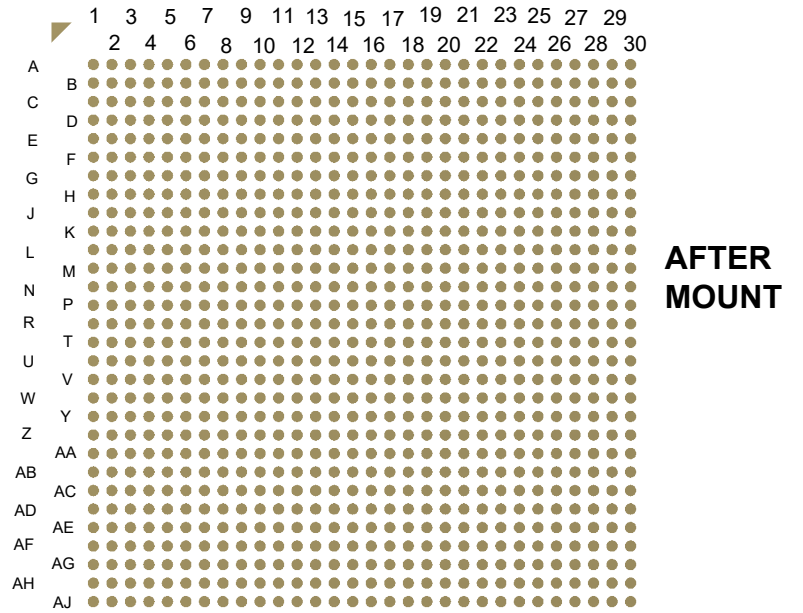
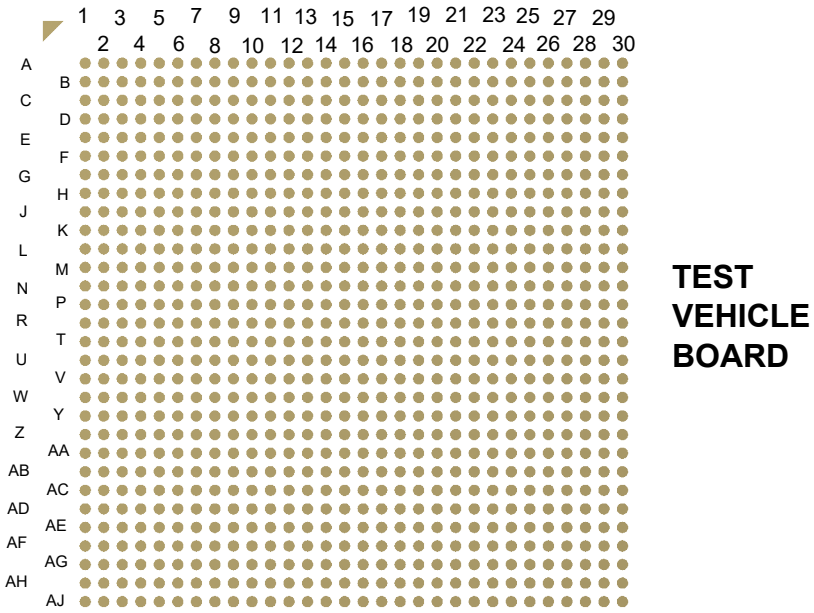
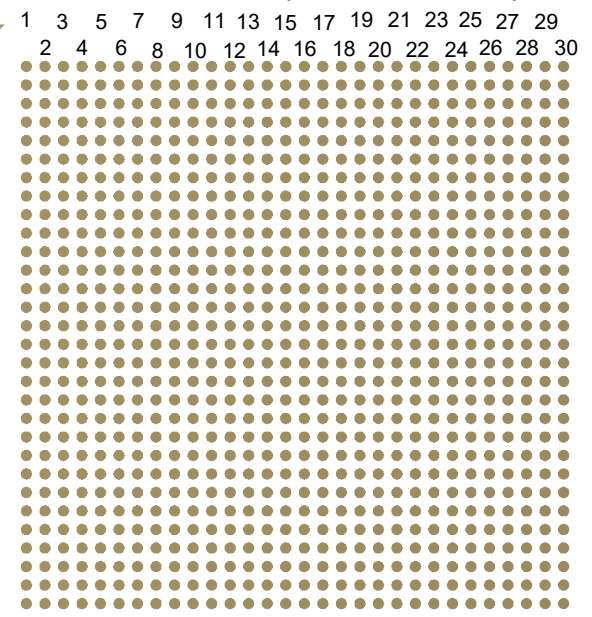
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
LBGA900T.35C-ISO	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
LBGA900T.35-ISO	Sn63/Pb37	NO	NO	NO

APPROVALS	DATE	TopLine®		
DRAWN T. Au	6/29/2023			
ENG M. Hart	6/29/2023	TITLE LBGA900T.35-ISO ISOLATED DUMMY BGA		
MFG		SCALE 40:1	SIZE A	DRAWING NO. 573007
QA				REV A
CUST				
REVISED		DO NOT SCALE DRAWING		SHEET 1 OF 3

BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)

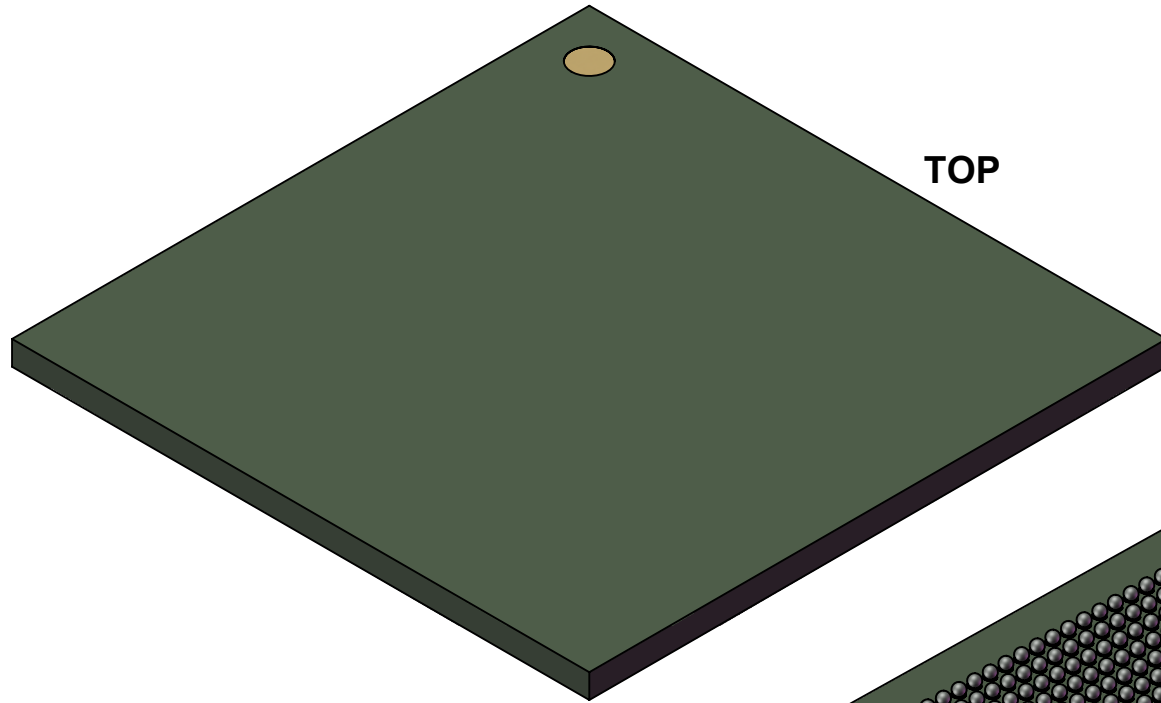


Notes:

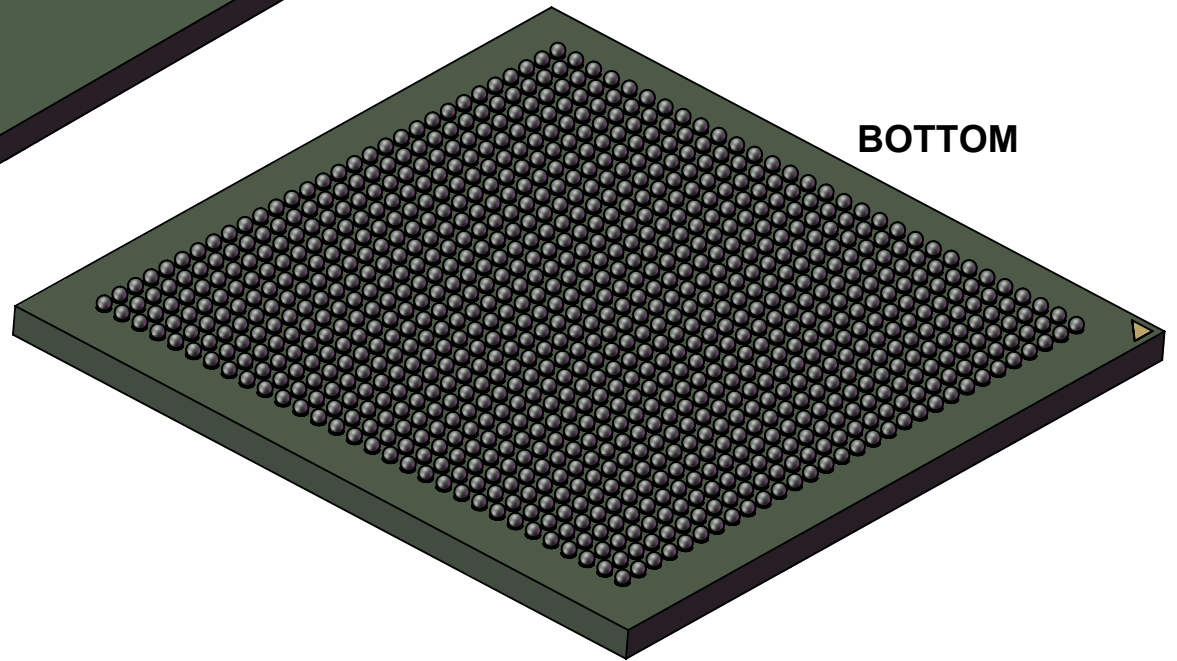
- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER: $\varnothing 0.25\text{mm}$ (10 mil).
- 3) PCB TRACING LINE WIDTH: 0.127mm (5 mil).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.20mm (8 MIL).

TopLine[®]			
TITLE		LBGA900T.35-ISO ISOLATED DUMMY BGA	
SCALE	SIZE	DRAWING NO.	REV
25:1	A	573007	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

MODEL



TOP



BOTTOM

TopLine[®]

TITLE LPGA900T.35-ISO
ISOLATED DUMMY BGA

SCALE	SIZE	DRAWING NO.	REV
40:1	A	573007	A

DO NOT SCALE DRAWING

SHEET 3 OF 3